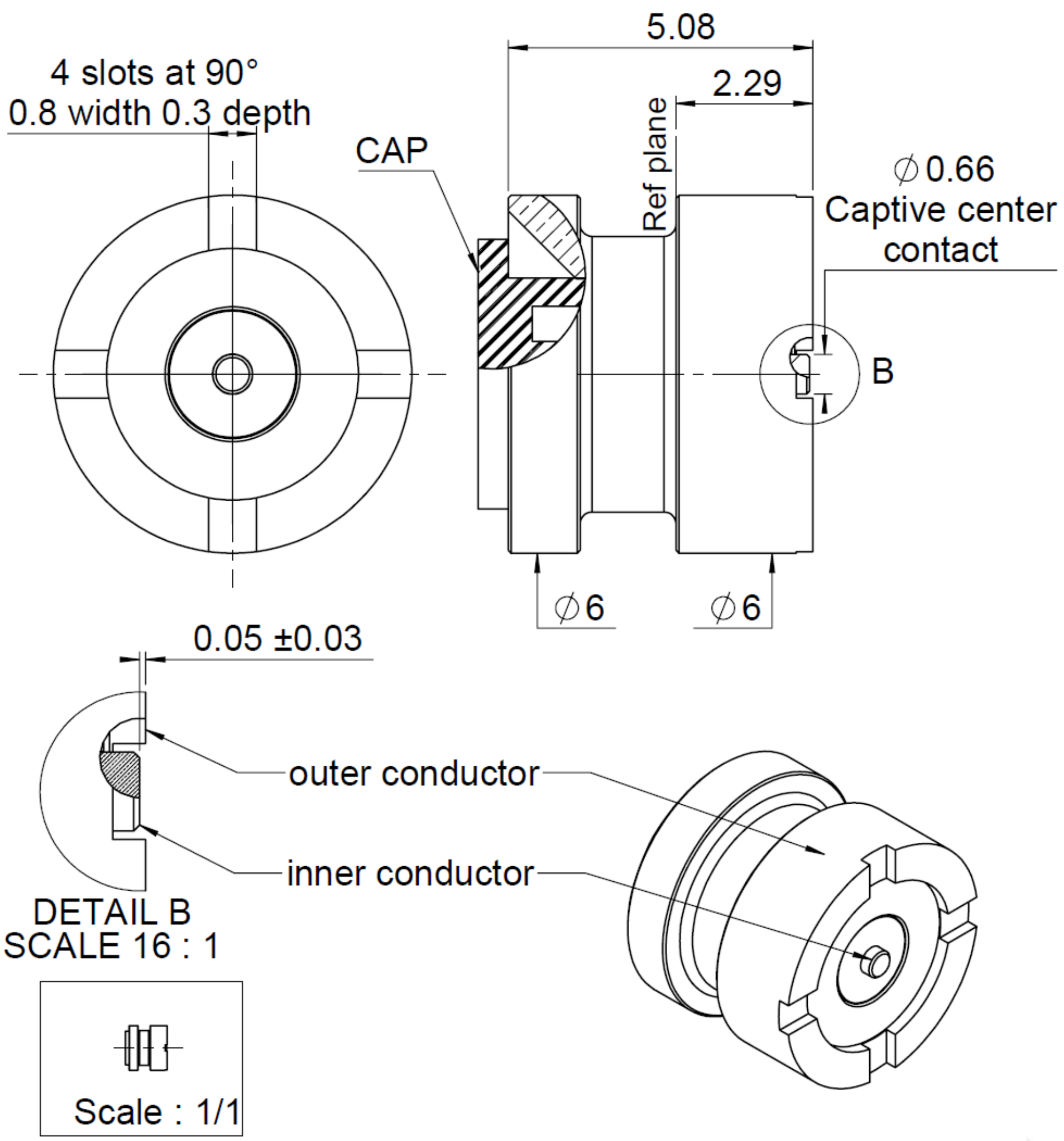
Technical Data Sheet

STRAIGHT MALE RECEPTACLE SMT SMOOTH BORE BY 500

PAGE **1/5**	ISSUE **23-07-25A**	SERIES **SMP**	PART NUMBER **RS03408000**



All dimensions are in mm. Tolerances according ISO 2768 m-H

COMPONENTS	MATERIALS	PLATING (µm)
Body	**BRASS**	**NPGR**
Center contact	**BERYLLIUM COPPER**	**N2PGR**
Outer contact		
Insulator	**PTFE**	
Gasket		
Others parts		
-	-	-
-	-	-

PACKAGING

Standard	Unit	Other
500	**Contact us**	**Contact us**

ELECTRICAL CHARACTERISTICS

Impedance	**50**	Ω
Frequency	**0-18**	GHz
VSWR	**1.03*** **+** **0.0200**	x F(GHz) Maxi
Insertion loss	**0.02+0.12***	√F(GHz) dB Maxi
RF leakage	- (**NA**	- F(GHz)) dB Maxi
Voltage rating	**335**	Veff Maxi
Dielectric withstanding voltage	**500**	Veff mini
Insulation resistance	**5000**	MΩ mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	**6.7**	N mini
Axial force – Opposite end	**6.7**	N mini
Torque	**NA**	N.cm mini
Recommended torque		
Mating	**NA**	N.cm
Panel nut	**NA**	N.cm
Mating life	**100**	Cycles mini
Nominal Weight (Add +15% for max weight)	**0.77**	g

ENVIRONMENTAL

Operating temperature	**-65/+165**	°C
Hermetic seal	**NA**	Atm.cm3/s
Panel leakage	**NA**	

SPECIFICATION

RAD-GEN-CONN-004

OTHER CHARACTERISTICS

Assembly instruction:

Others:
***Coaxial Transmission Line Only**
Performance strongly depends on layout and PCB material

CUSTOMER APPROVAL

Company / department:

Name /date/signature:

Signed copy to be sent back to Radiall before any order.
Note : In case of compliant matrix, it must be signed and sent back too

SOLDER PROCEDURE

1. **Deposit solder paste ‘SnAg4Cu0.5’ on mounting zone by screen printing application.**
   We recommend a low residue flux.
   We advise a thickness of 150 µm. Verify that the edges of the zone are clean.

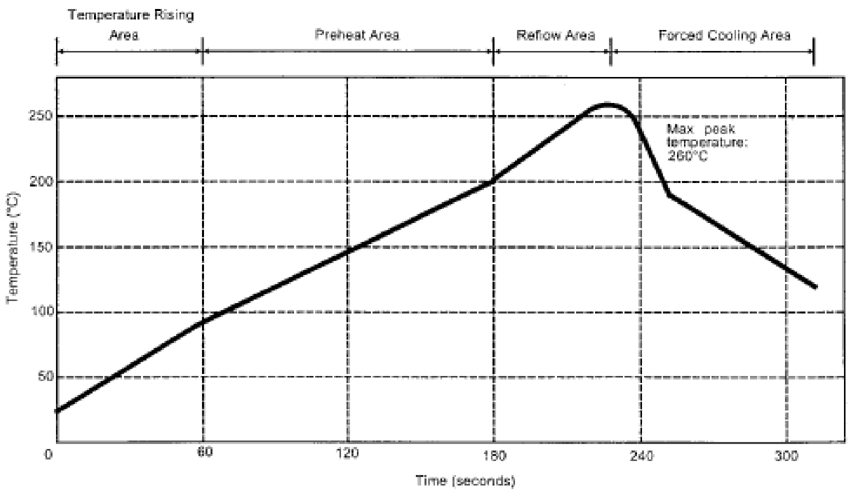
2. **Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.**

3. **This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.**

4. **The cleaning of printed circuit boards is not obliged .**

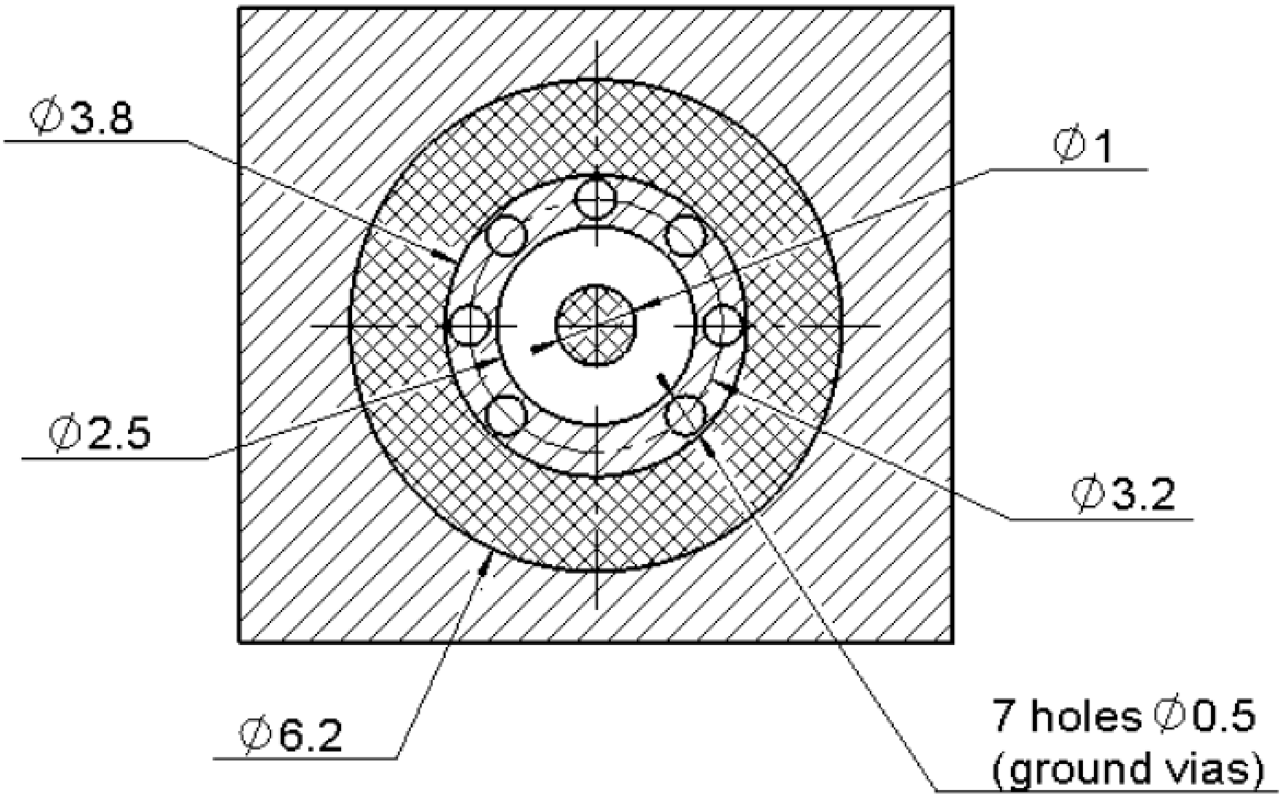
5. **Verification of solder joints and position of the component by visual inspection.**

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

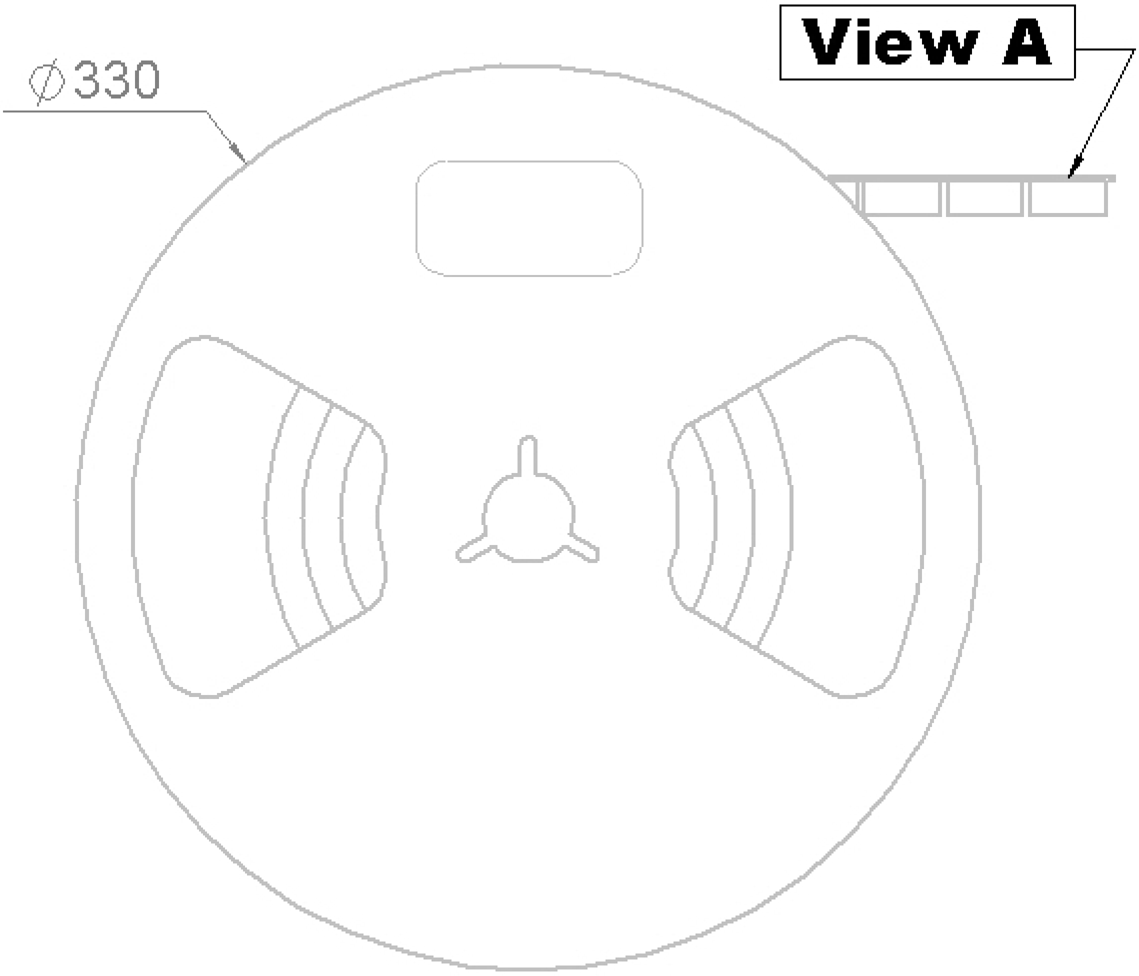
RT DUROID 6002 (30 mils) PAD (RADIALL RECOMMANDATION)



▦ Land for solder past

▨ Ground + varnish

-The landing pad for center contact should be linked to the stripline using a filled via.
-Upper and lower ground planes should be linked using vias.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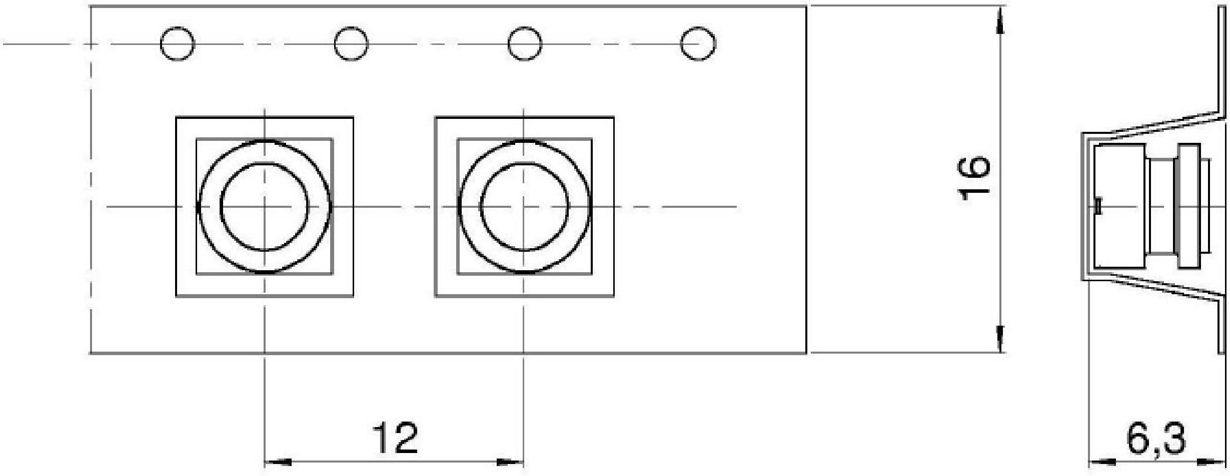
View A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